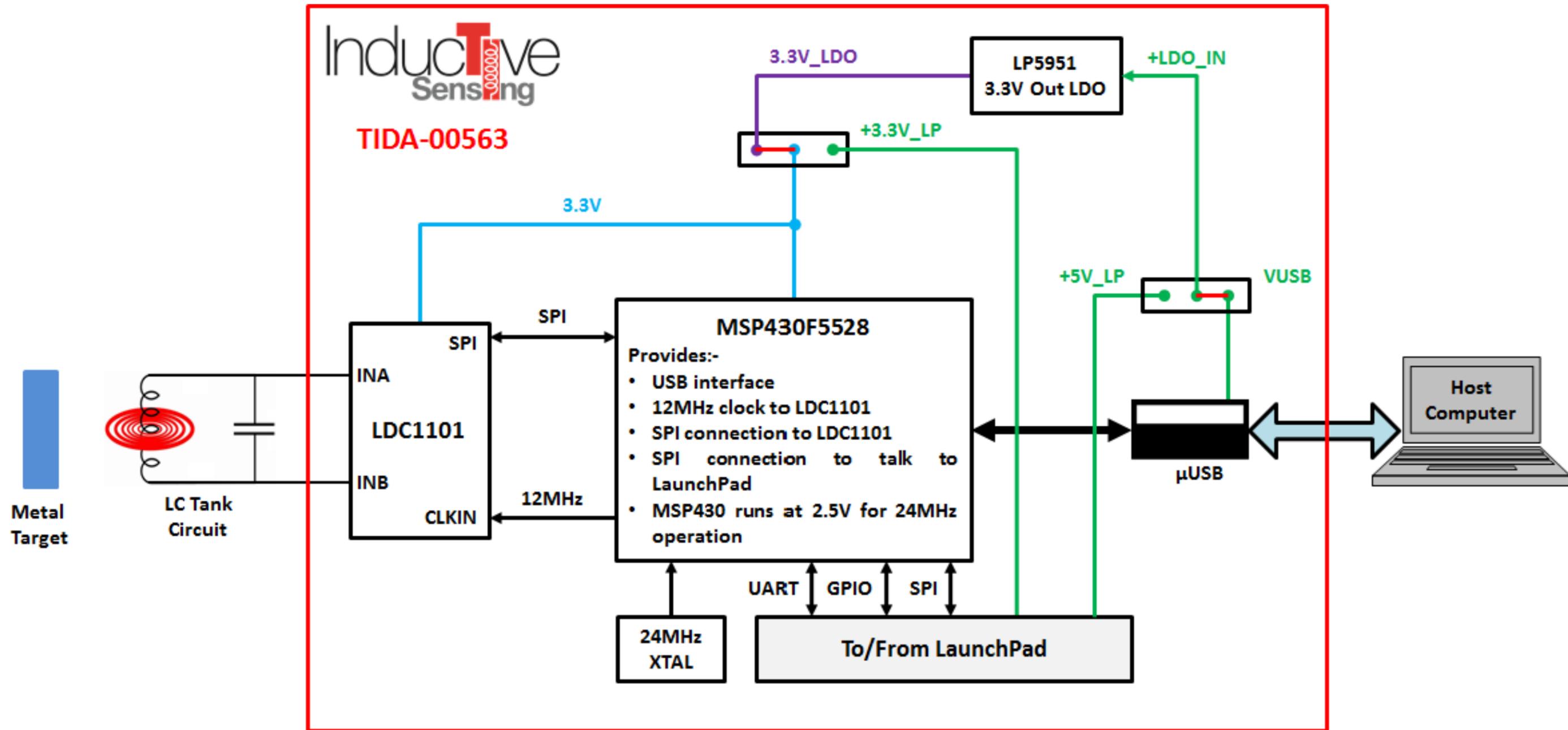
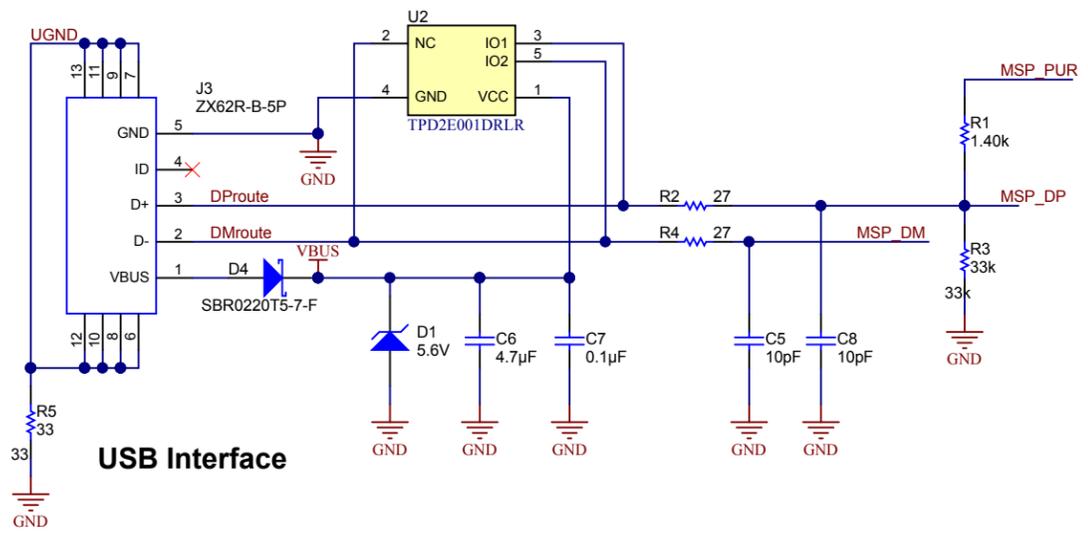


Revision History				
Rev	ECN #	Approved Date	Approved by	Notes
N/A	N/A	N/A	N/A	N/A

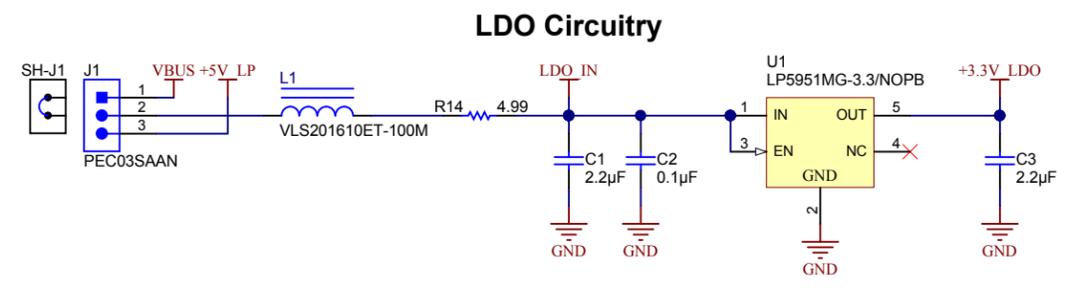


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TID #: TIDA-00563	Project Title: Inductive Proximity Switch BoosterPack		
Number: TIDA-00563	Rev: E1	Sheet Title: Block Diagram	
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 1 of 3	
Drawn By: SY	File: TIDA-00563_E1_CoverSheet.SchDoc	Size: B	
Engineer: FA&C	Contact: http://www.ti.com/support		

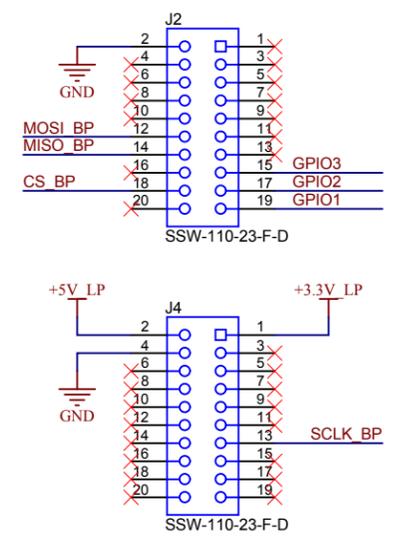


USB Interface



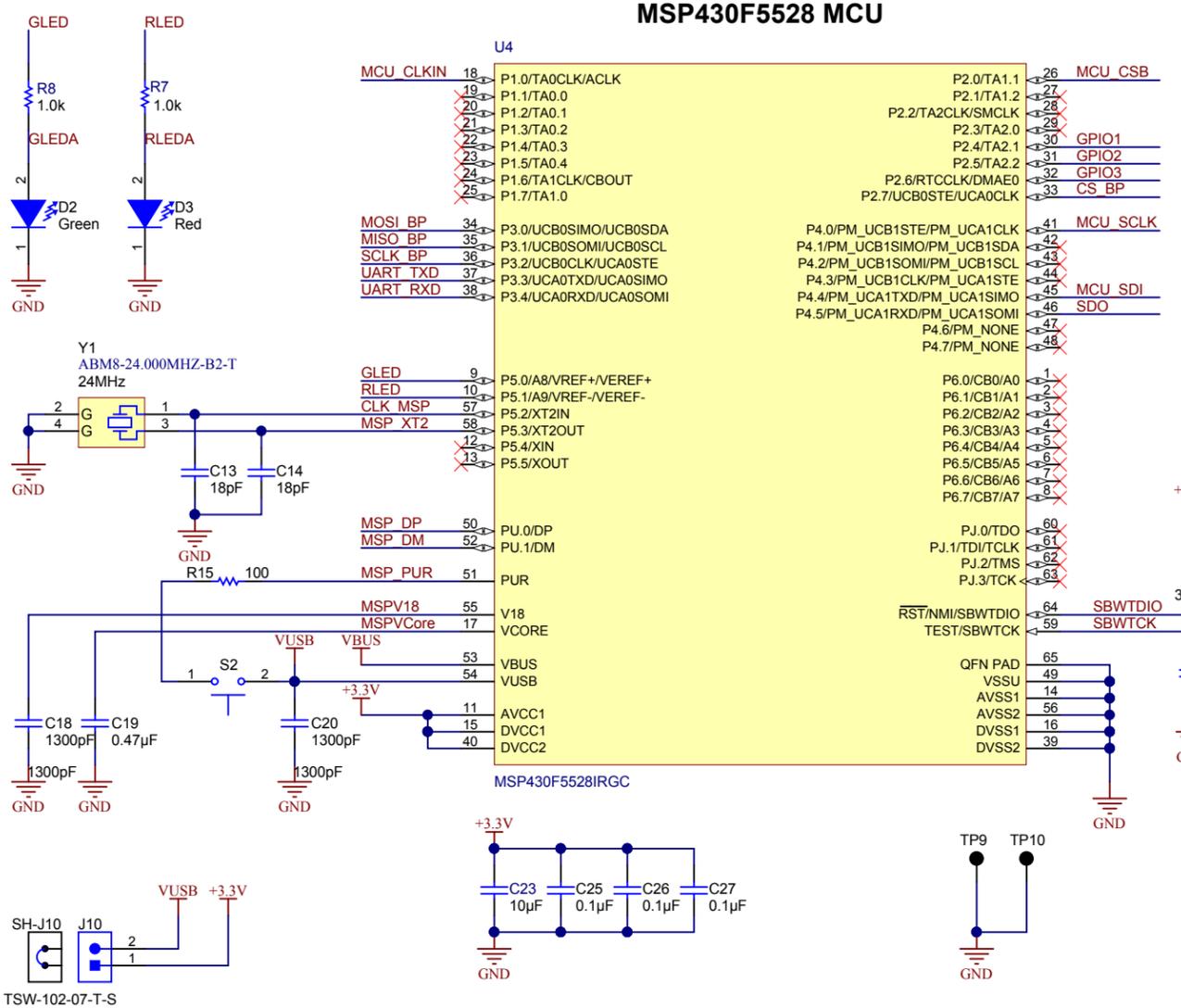
LDO Circuitry

BoosterPack Interface Connector

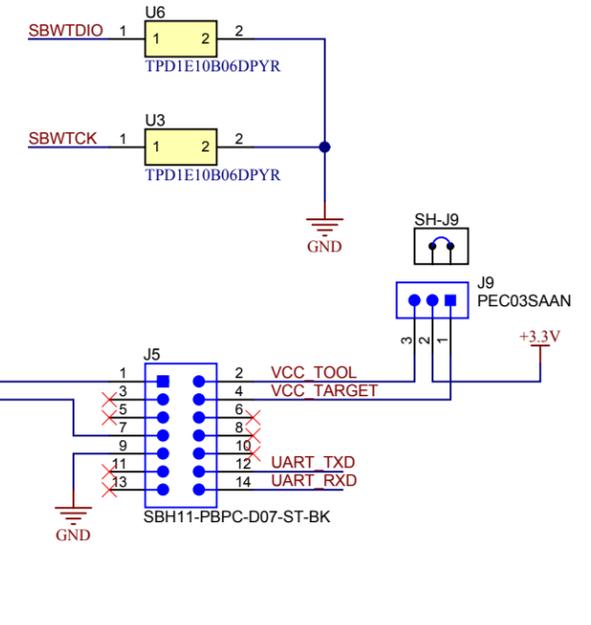


TIDA-00460 Powered By	J1	J7	J9	J10
+3.3V from Launch Pad	Don't Care	Short 2-3	Short 1-2	Open
+5V from Launch Pad	Short 2-3	Short 1-2	Short 1-2	Open
MSP430 FET Tool	Don't Care	All Open	Short 2-3	Open
VBUS	Short 1-2	Short 1-2	Short 1-2	Open
VBUS & MSP430's Built-in LDO	Don't Care	All Open	Short 1-2	Short 1-2

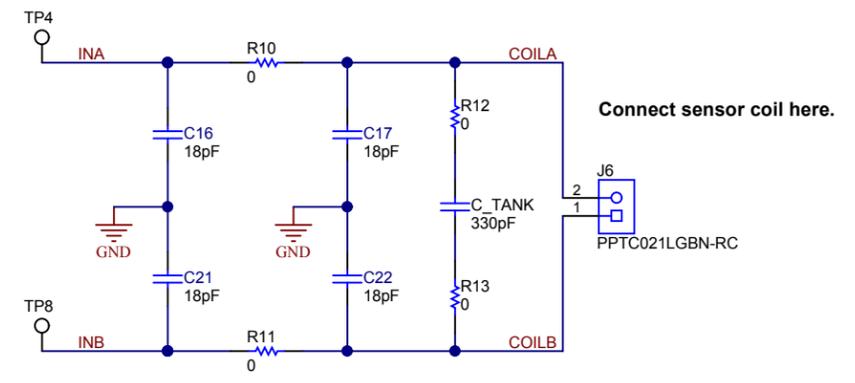
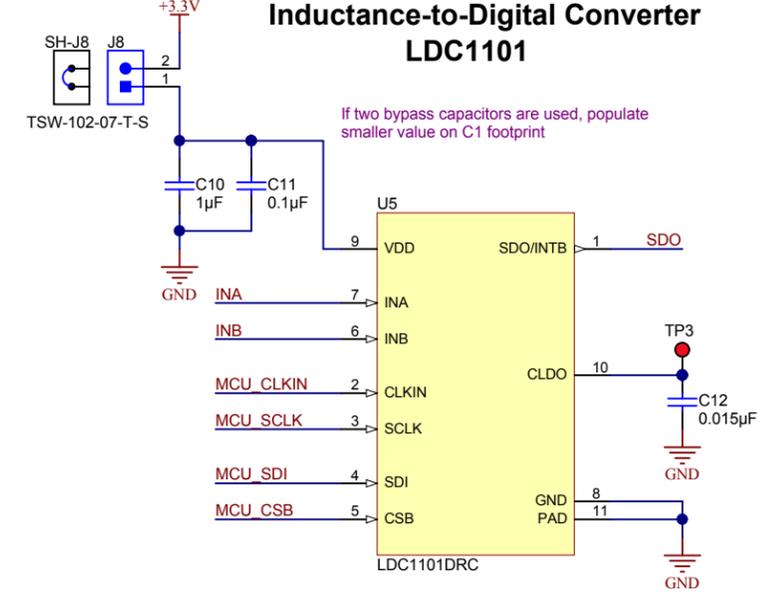
MSP430F5528 MCU



Spy-bi-wire Interface & ESD Protection



Inductance-to-Digital Converter LDC1101



Connect sensor coil here.

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DNP
FID1 DNP
FID2 DNP
FID3

PCB Number: TIDA-00563
PCB Rev: E1

PCB
LOGO
Texas Instruments

PCB
LOGO
ESD Susceptible

Label Table	
Variant	Label Text
001	TIDA-00563 REV: E1

ZZ1
Label Assembly Note
This Assembly Note is for PCB labels only

ZZ2
Assembly Note
This Assembly Note will show in the PcbDoc and associated outputs

ZZ3
Assembly Note
This Assembly Note will show in the PcbDoc and associated outputs

ZZ4
Assembly Note
This Assembly Note will show in the PcbDoc and associated outputs

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TID #: TIDA-00563	Project Title: Inductive Proximity Switch BoosterPack		
Number: TIDA-00563	Rev: E1	Sheet Title: Hardware	
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 3 of 3	
Drawn By: SY	File: TIDA-00563_E1_Hardware.SchDoc	Size: B	
Engineer: FA&C	Contact: http://www.ti.com/support		

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